

CBR06C708BAGAC

CBR-SMD RF COG, Ceramic, 0.7 pF, +/-0.1 pF, 250 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0603



Click here for the 3D model.

| Dimensions | | |
|------------|-----------------|--|
| Chip Size | 0603 | |
| L | 1.6mm +/-0.1mm | |
| W | 0.8mm +/-0.1mm | |
| Т | 0.8mm +/-0.07mm | |
| В | 0.4mm +/-0.15mm | |

| Packaging Specifications | |
|--------------------------|--------------------------|
| Packaging | T&R, 180mm, Plastic Tape |
| Packaging Quantity | 4000 |

| General Information | |
|---------------------|--|
| Series | CBR-SMD RF COG |
| Style | SMD Chip |
| Description | SMD, Fixed, RF, Ultra High Q, Low ESR, Class I |
| Features | Ultra High Q, Low ESR, Class I |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Component Weight | 5.6 mg |
| Notes | Solder Wave or Solder Reflow. |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Specifications | |
|---------------------------------|---------------------|
| Capacitance | 0.7 pF |
| Capacitance Tolerance | +/-0.1pF |
| Voltage DC | 250 VDC |
| Dielectric Withstanding Voltage | 500 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | COG |
| Dissipation Factor | 0.242% |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 10 GOhms |
| Quality Factor | 414 |

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